DecaBDE Statement
Texas Instruments Semiconductor Products

As of June 30, 2008 the Decabromodiphenyl ether (DecaBDE) exemption referenced in European Commission Decision of 13 October 2005 (2001/717/EC), will no longer be valid as a EU RoHS exemption. In response to the removal of this exemption, Texas Instruments (TI) would like to convey to its customers that TI integrated circuits do not contain DecaBDE. This information represents TI's knowledge and belief as of the date that is provided. TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information, but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals.

Sincerely,

Mark Frimann
TI SC Product Stewardship Management

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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